



Memory Module Specifications

16G DDR4-3200

16GB 1Rx8 2G x 64-Bit PC4-3200
CL22 288-Pin DIMM

DESCRIPTION

This document describes Memory Module is a 2G x 64-bit (16GB) DDR4-3200 CL22 SDRAM (Synchronous DRAM), 1Rx8, memory module, based on eight 2G x 8-bit FBGA components. The SPD is programmed to JEDEC standard latency DDR4-3200 timing of 22-22-22 at 1.2V. Each 288-pin DIMM uses gold contact fingers. The electrical and mechanical specifications are as follows:

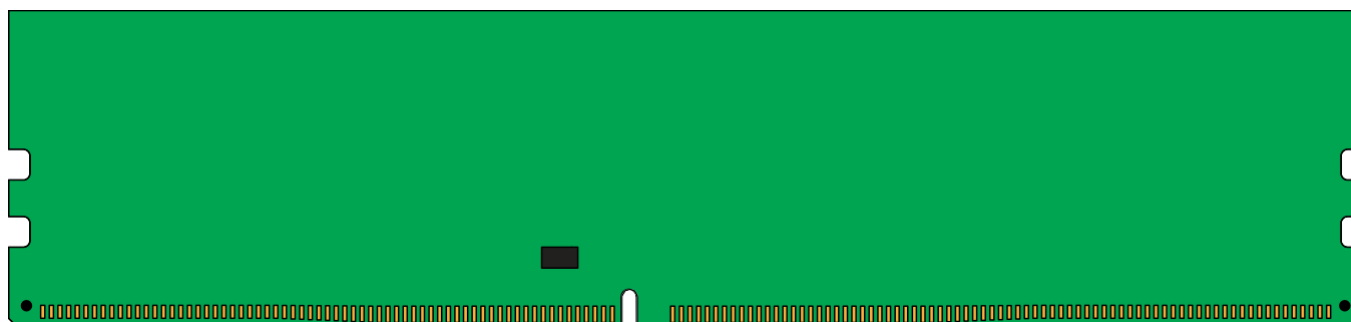
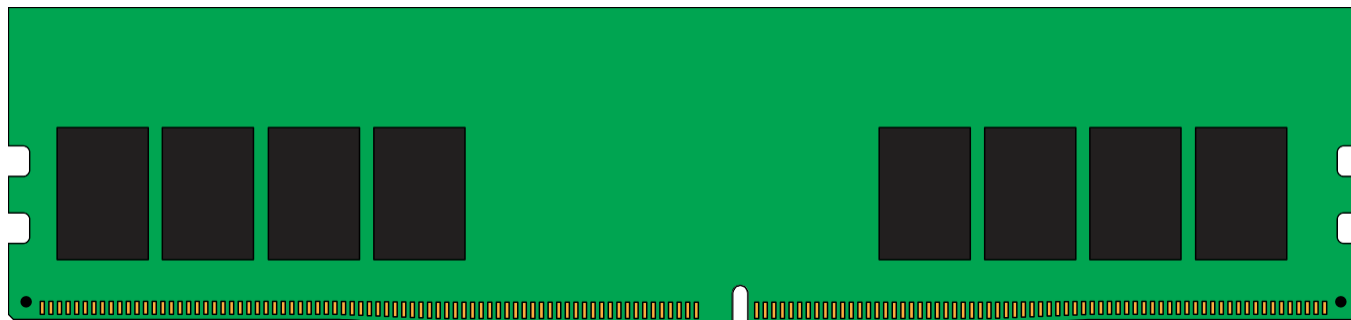
FEATURES

- Power Supply: VDD = 1.2V Typical
- VDDQ = 1.2V Typical
- VPP = 2.5V Typical
- VDDSPD = 2.2V to 3.6V
- Nominal and dynamic on-die termination (ODT) for data, strobe, and mask signals
- Low-power auto self refresh (LPASR)
- Data bus inversion (DBI) for data bus
- On-die VREFDQ generation and calibration
- Single-rank
- On-board I2 serial presence-detect (SPD) EEPROM
- 16 internal banks; 4 groups of 4 banks each
- Fixed burst chop (BC) of 4 and burst length (BL) of 8 via the mode register set (MRS)
- Selectable BC4 or BL8 on-the-fly (OTF)
- Fly-by topology
- Terminated control command and address bus
- PCB: Height 1.23" (31.25mm)
- RoHS Compliant and Halogen-Free

SPECIFICATIONS

CL(1DD)	22 cycles
Row Cycle Time (tRCmin)	45.75ns(min.)
Refresh to Active/Refresh Command Time (tRFCmin)	350ns(min.)
Row Active Time (tRASmin)	32ns(min.)
UL Rating	94 V - 0
Operating Temperature	0° C to +85° C
Storage Temperature	-55° C to +100° C

MODULE DIMENSIONS



All measurements are in millimeters.
(Tolerances on all dimensions are ± 0.12 unless otherwise specified)

